Compliant with IEC 62474/ D9.00

MICROCHIP Semiconductor Device Type: OT / CH / OTY (6AX) 006 SOT-23 NiPdAu			Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)				JEDEC 97 Product Marking and/or Pkg. Labeling
Semiconductor Device 1	ype: OT / CH / OTY	(6AX) 006 SOT-23 NiPdAu								e4
		"Contained In"	% Total							
Basic Substance	CAS Number	Sub-Component	Weight	mg/part	ppm	7.94	(mg) Total	Mold Compound	% ot Total Weight	48.26
Silica, vitreous (or fused)	60676-86-0	Mold Compound	41.021	6.748	410,210		Silica, vitreous (or fused)	60676-86-0	85.00	
Epoxy Resin	Trade Secret	Mold Compound	4.199	0.691	41,986		Epoxy Resin	Trade Secret	8.70	
Phenolic Resin	Trade Secret	Mold Compound	2.896	0.476	28,956		Phenolic Resin	Trade Secret	6.00	
Carbon Black	1333-86-4	Mold Compound	0.145	0.024	1,448		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	48.319	7.949	483,192			Total	100.00	<u>.</u>
Iron	7439-89-6	Lead Frame	1.142	0.188	11,422	8.17	(mg) Total	Lead Frame	% of Total Weight	49.66
Phosphorous	7723-14-0	Lead Frame	0.124	0.020	1,242	0	Copper	7440-50-8	97.30	10.00
Zinc (Metal)	7440-44-0	Lead Frame	0.074	0.012	745		Iron	7439-89-6	2.30	
Aluminum oxide	1344-28-1	Die Attach	0.143	0.012	1,435		Phosphorous	7723-14-0	0.25	
Epoxy resin	Trade Secret	Die Attach	0.143	0.024	2.609		Zinc (Metal)	7440-44-0	0.25	
Amine (Trade Secret - 10039)	Trade Secret	Die Attach	0.261	0.003	157		Ziric (ivietal)	7440-44-0 Total		1
Silicon	7440-21-3	Chip (Die)	1.090	0.179	10,900	0.07	(mg) Total	Die Attach	% of Total Weight	0.42
Gold	7440-57-5	Wire Bond	0.120	0.020	1,200		Aluminum oxide	1344-28-1	34.16	
Nickel	7440-02-0	Plating on external leads (pins)	0.431	0.071	4,308		Epoxy resin	Trade Secret	62.11	
Palladium	7440-05-3	Plating on external leads (pins)	0.015	0.002	145	Aı	mine (Trade Secret - 10039)	Amine (Trade Secret - 10039)	3.73	
Gold	7440-57-5	Plating on external leads (pins)	0.005	0.001	47			Total	100.00	_
		TOTALS	100.000	16.450	1,000,000	0.18	Total (mg)	Chip (Die)	% of Total Weight	1.09
	0.0405									
		Total Mass					Doned Silicon	7440-21-3	100.00	
2002/53/EC (End-of-Life Vehicles (ELV) without exemption	mply with EU Directives: 2002/95 n (zero)	,	une 2011) and 20	015/863/EU (31	March 2015)	0.02	Doped Silicon (mg) Total	7440-21-3 Total Wire Bond	100.00 100.00 % of Total Weight	0.12
semiconductor device and its homogenous materials coi 2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified vihemical substance is absent from the list above, the cher porated's knowledge and belief as of the date of this doc	mply with EU Directives: 2002/95, n (zero) a internal design controls, suppli mical substance is NOT an intent ument, there is no credible reasc	EC (27 January 2003) & Directive 2011/65/EU (08 J ier declarations, and /or analytical test data. ional ingredient in the semiconductor device and, to	o the best of Mic	rochip Techno	logy	0.02		Total	100.00	0.12
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2002/53/EC (End-of-Life Vehicles (ELV) without exemption pliance with the above EU Directives has been verified vinhemical substance is absent from the list above, the cher porated's knowledge and belief as of the date of this docelow the threshold of regulatory concern for any regulate ing compounds used by Microchip meet the UL94 V0 flar (/ul.com/global/eng/pages/offerings/industries/chemicals or ortective "tubes" in which the specific product is shipped in "reels" may be made from PVC plastic. Dechip Technology Incorporated believes the information is nail packing materials is true and correct to the best of its beleteness and accuracy of data in this form because it hamation is often protected from disclosure as trade secret ded only as estimates of the average weight of these parnts, metals, and non-metal materials contained within sile or the protected from the provide any warded by Microchip Technology Incorporated and its subsiler acknowledgement, and invoices.	mply with EU Directives: 2002/95, in (zero) a internal design controls, supplimical substance is NOT an intent nument, there is no credible reasony scheme world-wide. Immability standard for plastics. Yet are made from polyvinyl chlorical thin this form concerning substance, knowledge and belief, as of the is been compiled based on the rase and some information may not sand the average weight of anticon devices (silicon IC) in the file ranty, express or implied, with rediaries are contained in Microchianges to Material Content Declarance on the information in Materia	let (27 January 2003) & Directive 2011/65/EU (08 Jet declarations, and /or analytical test data. It declarations, and /or analytical test data. It is important in the semiconductor device and, to the believe that the unavoidable impurity concentry out can access the UL iQTM family of databases to declare (PVC) plastic. "Window envelopes" used to hold the earnest in this form. Microchip Technology Incordate listed in this form. Microchip Technology Incordated significant toxic metals components. These anished parts. It is a sepect to the information provided in this declaration is standard terms and conditions of sale. These are attions and shall not be liable for any damages, direct all Content Declarations (MCD) or independent third	o the best of Mication of the cher obtain a test report the packing slip orporated's semi- porated cannot gived by raw mater of raw material site estimates do not not the control of the	rochip Technol nical substanc ort at on the outer to conductor dev guarantee the lal suppliers. Si pppliers. Inforn to include trace cochip's quot asequential or	logy e, if any, is cox and vices in their supplier nation is e levels of ct warranties ations, sales otherwise,		(mg) Total Doped Gold (mg) Total Nickel	Wire Bond 7440-57-5 Total Plating on external leads (pins) 7440-02-0 7440-05-3	100.00 % of Total Weight 100.00 100.00 % of Total Weight 95.73 3.23	0.45

Au 10:16 AM : 8/17/2015